Special Issue

Semiconductor and Package for Next Generation

Message from the Guest Editors

Dear colleagues, Semiconductor processes use nanometer technology to increase circuit integration and process at high speed, with the development of 5G/6G aimed at gigabits per second. In addition, process and design technologies are being developed to secure high power levels, and reliability improvement is essential in the automobile semiconductor field. This should be researched and developed not only with semiconductors but also with packages. This Special Issue deals with the process and design technology of semiconductors and packages that improve the speed, density, power, and reliability of various applications. I hope there will be many publications by the authors of theoretical and application-oriented papers that present new ideas and technologies to solve various unresolved problems and challenges relating to semiconductors and packages.

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Message from the Editor-in-Chief

Electronics is a multidisciplinary journal designed to appeal to a diverse audience of research scientists, practitioners, and developers in academia and industry. The journal is devoted to fast publication of latest technological breakthroughs, cutting-edge developments, and timely reviews of current and emerging technologies related to the broad field of electronics. Experimental and theoretical results are published as regular peer-reviewed articles or as articles within Special Issues guestedited by leading experts in selected topics of interest.

Editor-in-Chief

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